



## HexPly® M949

Next Generation Cosmetic Prepreg for Automotive

**HEXCEL®**

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Next-Generation Cosmetic Prepreg for Automotive



HexPly® M949 is designed for the **automotive sector**,  
**offering many benefits:**

- Suitable for **all visible carbon applications**
- Created for **high-quality exterior and interior cosmetic parts**
- Parts can be cured in the **press or autoclave**
- Suitable for parts exposed to **elevated temperatures**

## Toughened Epoxy Prepreg for High-Quality Carbon-Look Surfaces

PREPREG COMPRESSION MOLDING  
AND AUTOCLAVE PROCESS

MULTIPLE LINES QUALIFIED  
CAMERA VISION SYSTEM

EXCELLENT  
SURFACE FINISH

WEIGHT SAVINGS VS  
TRADITIONAL COSMETIC LAYERS

HexPly®  Nature Range

HOT-MELT CHEMISTRY  
15% BIO-BASED CARBON CONTENT IN M949 RESIN\*  
LIFE CYCLE ASSESSMENT (LCA) AVAILABLE

FREE OF PINHOLES  
AND WHITE SPOTS

HIGH TG >145°C

LONG OUTLIFE: 21 WEEKS  
AT ROOM TEMPERATURE

\*Bio-based Carbon Content certified following ASTM D6866-24 standard method:  
Determining the Biobased Content of Solid, Liquid, and Gaseous Samples Using Radiocarbon Analysis

# Key Features

## Resin Matrix Properties

- Dynamic Thermal Properties by DSC<sup>(1)</sup>

Uncured Tg	-5 to +1°C
TOnset	140 – 150°C
TPeak	145 – 155°C
Enthalpy	340J/g ± 20%

- Typical cured Tg >145°C (following a 90min cure @140°C)<sup>(2)</sup>
- Density (ISO 1183-1) 1.15 – 1.20g/cm<sup>3</sup>
- Hot-Wet Performance<sup>(3)</sup>
  - Tg Dry<sup>(2)</sup> 150 ± 5°C
  - Tg Hot-Wet<sup>(2)</sup> 125 ± 5°C
- Shelf Life<sup>(4)</sup>
  - @ +23°C 21 weeks
  - @ +5°C ≥ 6 months
  - @ -18°C ≥ 18 months

(1) According to ISO 11357-2 using a 10°C/min ramp rate, -40 to 270°C

(2) Measured by DMTA according to ASTM E-1640-09 @10°C/min, Maximum Loss Modulus (E'')

(3) 2 weeks at 70°C, specimens immersed in water

(4) Stored sealed, in dry conditions and in absence of direct sunlight. Shelf Life refers to the minimum time at given temperature after which the resin is being impaired in its thermal or rheological properties. An increase in uncured Tg above NTP temperature limitation (NIST) defines the end of shelf life of the resin matrix

## Recommended typical Curing Conditions

	Cure Cycle	Tg <sup>(4)</sup>
Autoclave	Ramp up 2°C/min, 60-90 min @130-140°C, 7 bar	>145°C
PCM	15 to 30 min @130-140°C (hot in/hot out), 10 bar	>145°C

The optimum cure cycle, heat-up rate, dwell period and pressure are dependent on component size, shape, layup construction, oven capacity and thermal mass of tool. Higher temperature cure cycles than 140°C are not recommended.

## For more information

Hexcel is a leading worldwide supplier of composite materials to aerospace and industrial markets.

Our comprehensive range includes:

- HexTow® carbon fibers
- HexForce® reinforcements
- HexPly® preprints
- HexAM® additive manufacturing
- HexMC® molding compounds
- HexFlow® RTM resins
- HexBond® adhesives
- HexTool® tooling materials
- HexWeb® honeycomb
- Acousti-CAP® sound attenuating honeycomb

- Engineered core
- Engineered products
- Polyspeed® laminates & pultruded profiles
- TowPly™ towpreg
- HexShape™ preforms

For US quotes, orders and product information call toll-free 1-800-688-7734. For other worldwide sales office telephone numbers and a full address list, please go to:

<https://www.hexcel.com/contact>

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